



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-06-15
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*0158BG6	A	BO2A	2018-06-15
Amount	UoM	Unit type	ST ECOPACK Grade	
34.00	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au/Ag)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4X3.0X0.9	8	gull wing	
Comment	TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for LM258PT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*0158B66						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	0.718	mg	supplier	die	Silicon (Si)	7440-21-3		0.705	mg	981894	20735	
Die				supplier	metallization	Aluminum (Al)	7429-90-5		0.006	mg	8357	176	
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	4178	88	
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	5571	118	
Leadframe	Copper & its alloys	16.234	mg	supplier	alloy	Copper (Cu)	7440-50-8		15.529	mg	956573	456735	
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.484	mg	29814	14235	
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.024	mg	1478	706	
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.105	mg	6468	3088	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	5113	2441	
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	185	88	
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	185	88	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	185	88	
Die attach	Other Organic Materials	0.327	mg	supplier	glue	Silver (Ag)	7440-22-4		0.298	mg	911315	8765	
Die attach				supplier	glue	acrylate	Proprietary		0.016	mg	48930	471	
Die attach				supplier	glue	Methacrylate	Proprietary		0.013	mg	39755	382	
Bonding wire	Other inorganic materials	0.029	mg	supplier	wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	853	
encapsulation	Other Organic Materials	16.692	mg	supplier	mold compound	Silica, vitreous	60676-86-0		14.638	mg	876947	430529	
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		0.668	mg	40019	19647	
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		0.668	mg	40019	19647	
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.501	mg	30014	14735	
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.05	mg	2995	1471	
encapsulation				supplier	mold compound	additive	Proprietary		0.167	mg	10005	4912	